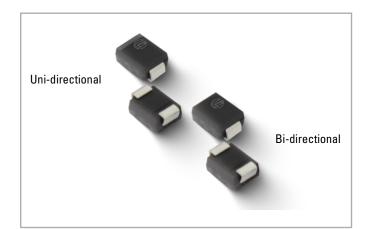
1.0SMB-Q Series Surface Mount - 1000W











Additional Information



Resources





Maximum Ratings and Thermal Characteristics

(T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation by 10/1000µs Waveform(Fig.1)(Note 1)(Note 2) -Single Die Parts	P _{PPM}	1000	W
Power Dissipation on Infinite Heat Sink at $T_L \! = \! 50 ^{\circ}\!\!\! \mathrm{C}$	P _D	5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I _{FSM}	100	А
Maximum Instantaneous Forward Voltage at 50A for Unidirectional Only	V _F	3.5	V
Operating Temperature Range	TJ	-55 to 150	$^{\circ}$
Storage Temperature Range	T _{STG}	-55 to 150	$^{\circ}$
Typical Thermal Resistance Junction to Lead	ReJL	20	°C/W
Typical Thermal Resistance Junction to Ambient	R _{OJA}	100	°C/W

Notes:

- 1. Non-repetitive current pulse , per Fig.3 and derated above T_J (initial) =25°C per Fig.2.
- 2. Mounted on copper pad area of 0.2x0.2" (5.0 x 5.0mm) to each terminal.
- 3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cvcle=4 per minute maximum.

Description

The 1.0SMB-Q series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events

Features

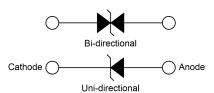
- High reliability application and automotive grade AEC-Q101 qualified
- 1000W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycles):0.01%
- Excellent clamping capability
- Low incremental surge resistance
- Typical I_R less than 1µA when V_B min>12V
- Optimized surface mount footprint for minimal PCB space impact
- Low profile package
- Typical failure mode due to exceeding maximum ratings is a short circuit condition
- Whisker test conducted based on Table 4a and 4c of JEDEC JESD201A
- ESD protection of data lines in accordance with IEC 61000-4-2, 30kV(Air), 30kV (Contact)

- EFT protection of data lines in accordance with IEC61000-4-4
- Built-in strain relief
- Fast response time: typically less than 1.0psfrom 0V to V_B
- High temperature to reflow soldering guaranteed: 260°C/20~40sec.
- $V_{B} @ T_{J} = V_{B} @ 25 ^{\circ}Cx (1 + \alpha T x)$ $(T_{\perp}$ - 25)) (α T:Temperature Coefficient, typical value is 0.1%)
- Meet MSL level1, per J-STD-020, LF maximum peak of 260°C
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD 609A.01)

Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{CC} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

Functional Diagram





1.0SMB-Q Series Surface Mount – 1000W

Electrical Characteristics (T_A=25 °C unless otherwise noted)

	art mber	Туре	Mar	vice king ode	Reverse Stand-Off Voltage	Vol	down tage I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _R
Uni.	Bi.		Uni.	Bi.	V _R (V)	V _{B MIn.} (V)	V _{B Max.} (V)	I⊤(mA)	V _c (V)	I _{PP} (A)	I _R (μA)
1.0SMB6.8A	1.0SMB6.8CA	Q	6V8A•	6V8C•	5.80	6.45	7.14	10	10.5	96.8	1000
1.0SMB7.5A	1.0SMB7.5CA	Q	7V5A•	7V5C∙	6.40	7.13	7.88	10	11.3	90.0	500
1.0SMB8.2A	1.0SMB8.2CA	Q	8V2A∙	8V2C•	7.02	7.79	8.61	10	12.1	84.0	200
1.0SMB9.1A	1.0SMB9.1CA	Q	9V1A•	9V1C•	7.78	8.65	9.55	1	13.4	75.8	50
1.0SMB10A	1.0SMB10CA	Q	10A•	10C•	8.55	9.50	10.50	1	14.5	70.2	10
1.0SMB11A	1.0SMB11CA	Q	11A•	11C•	9.40	10.50	11.60	1	15.6	65.2	5
1.0SMB12A	1.0SMB12CA	Q	12A•	12C•	10.20	11.40	12.60	1	16.7	60.8	5
1.0SMB13A	1.0SMB13CA	Q	13A•	13C•	11.10	12.40	13.70	1	18.2	55.8	1
1.0SMB15A	1.0SMB15CA	Q	15A∙	15C∙	12.80	14.30	15.80	1	21.2	48.0	1
1.0SMB16A	1.0SMB16CA	Q	16A•	16C•	13.60	15.20	16.80	1	22.5	45.2	1
1.0SMB18A	1.0SMB18CA	Q	18A∙	18C•	15.30	17.10	18.90	1	25.2	40.3	1
1.0SMB20A	1.0SMB20CA	Q	20A•	20C•	17.10	19.00	21.00	1	27.7	36.7	1
1.0SMB22A	1.0SMB22CA	Q	22A•	22C•	18.80	20.90	23.10	1	30.6	33.2	1
1.0SMB24A	1.0SMB24CA	Q	24A•	24C•	20.50	22.80	25.20	1	33.2	30.7	1
1.0SMB27A	1.0SMB27CA	Q	27A•	27C•	23.10	25.70	28.40	1	37.5	27.2	1
1.0SMB30A	1.0SMB30CA	Q	30A•	30C•	25.60	28.50	31.50	1	41.4	24.5	1
1.0SMB33A	1.0SMB33CA	Q	33A•	33C•	28.20	31.40	34.70	1	45.7	22.2	1
1.0SMB36A	1.0SMB36CA	Q	36A•	36C•	30.80	34.20	37.80	1	49.9	20.3	1
1.0SMB39A	1.0SMB39CA	Q	39A•	39C•	33.30	37.10	41.00	1	53.9	18.8	1
1.0SMB43A	1.0SMB43CA	Q	43A•	43C∙	36.80	40.90	45.20	1	59.3	17.2	1
1.0SMB47A	1.0SMB47CA	Q	47A•	47C•	40.20	44.70	49.40	1	64.8	15.7	1
1.0SMB51A	1.0SMB51CA	Q	51A•	51C•	43.60	48.50	53.60	1	70.1	14.5	1
1.0SMB56A	1.0SMB56CA	Q	56A•	56C•	47.80	53.20	58.80	1	77.0	13.2	1
1.0SMB62A	1.0SMB62CA	Q	62A●	62C•	53.00	58.90	65.10	1	85.0	12.0	1
1.0SMB68A	1.0SMB68CA	Q	68A•	68C•	58.10	64.60	71.40	1	92.0	11.0	1

Notes:

For bidirectional type having $V_{\mbox{\tiny R}}$ of 10 volts and less, the $I_{\mbox{\tiny R}}$ limit is double.



1.0SMB-Q Series Surface Mount - 1000W

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1: Peak Pulse Power Rating Curve

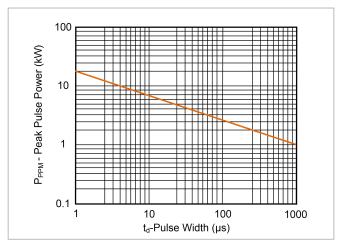


Figure 3: Pulse Waveform

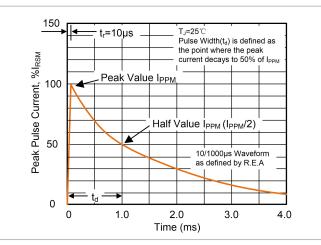


Figure 5:Steady State Power Dissipation Derating Curve

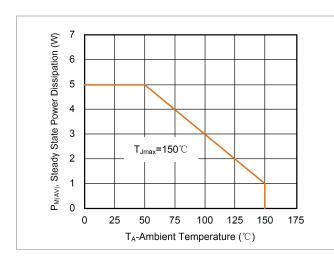


Figure 2: Pulse Derating Curve

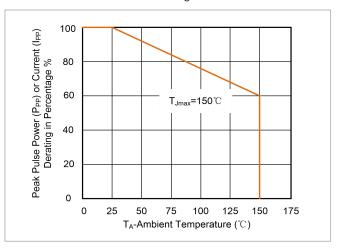


Figure 4: Typical Junction Capacitance

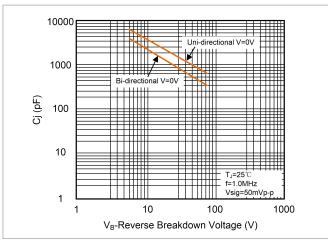
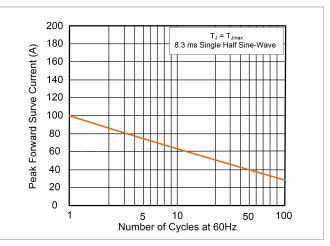


Figure 6: Maximum Non-Repetitive Forward Surge Current Uni-Directional

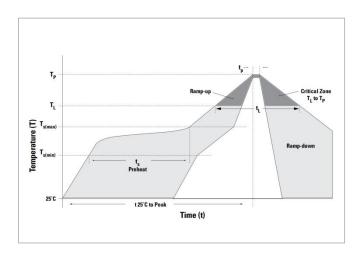




1.0SMB-Q Series Surface Mount – 1000W

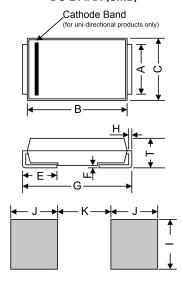
Soldering Parameters

Reflow Conditi	Lead-free assembly	
Pre Heat	-Temperature Min (T _{S min})	150℃
	-Temperature Max (T _{S max})	200℃
	-Time (min to max) (t _s)	60 – 180 secs
Average ramp-	3℃/second max.	
T _{S (max)} to T _L -Rai	3℃/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217℃
	-Time (min to max) (t _L)	60-150 seconds
Peak Temperat	260℃	
Time within 5°	20-40 seconds	
Ramp-down Ra	6°C/second max.	
Time 25℃ to P	8 minutes max.	
Do not exceed	260℃	



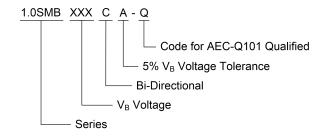
Dimensions

DO-214AA (SMB)

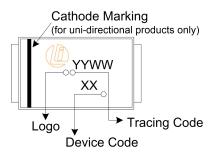


Cumbal	Millime	ters	Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.930	2.200	0.076	0.086	
В	4.060	4.570	0.160	0.180	
С	3.300	3.940	0.130	0.155	
E	0.760	1.520	0.030	0.060	
F	-	0.203	-	0.008	
G	5.100	5.480	0.201	0.216	
Н	0.152	0.305	0.006	0.012	
Т	2.160	2.440	0.085	0.096	
I	2.260	-	0.089	-	
J	2.160	-	0.085	-	
K	-	2.740	-	0.107	

Part Numbering System



Part Marking System



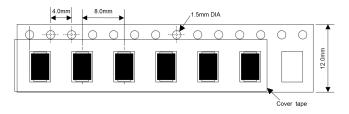


Packaging

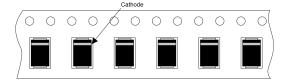
Part number	Component Package	Quantity	Packaging Option	Packaging Specification
1.0SMBxxxXX-Q	DO-214AA	3000	Tape & Reel - 12mm tape/13" reel	EIA STD RS-481

Tape and Reel Specification

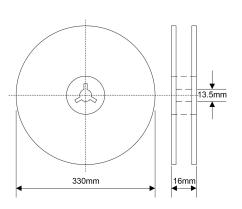
Tape



For Uni-Devices



13 Inches Reel



Quantity: 3000pcs/reel

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